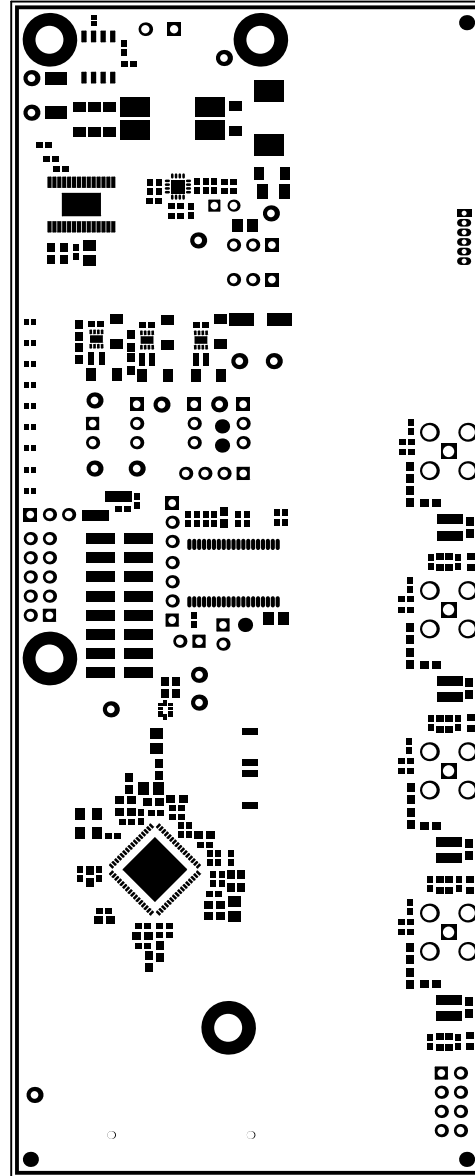
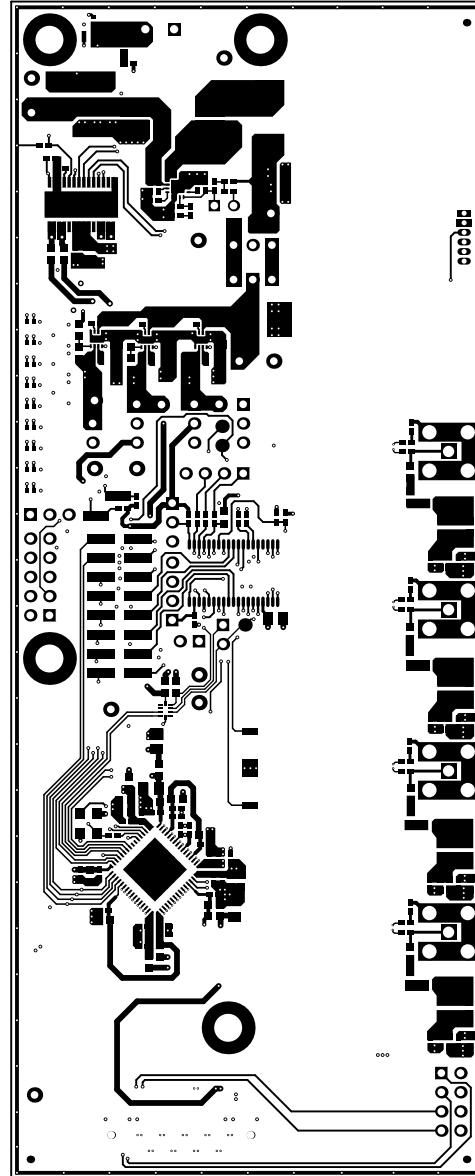


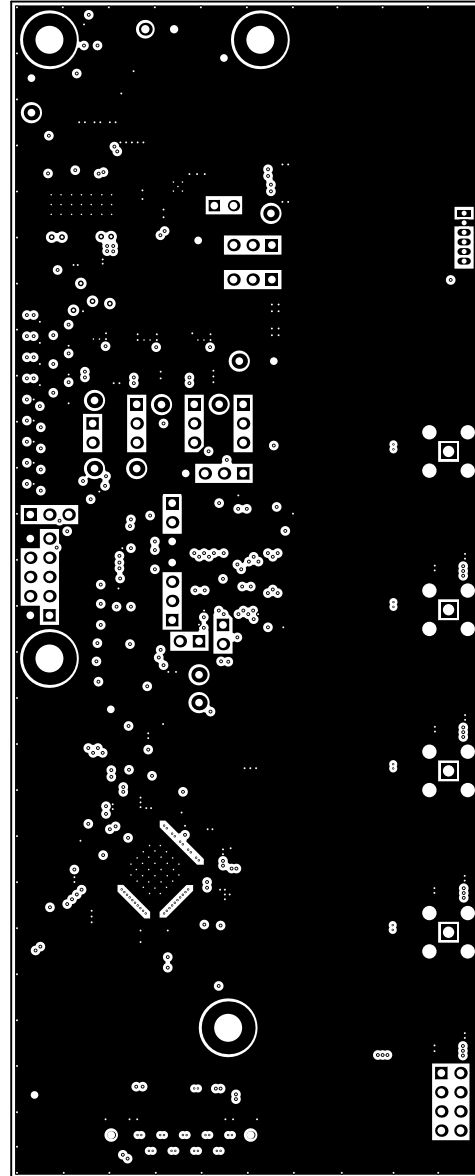
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01323	REV: E1.0	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 01323		
PLOT NAME = Top Overlay	GENERATED : 10/19/2017 2:04:27 PM	TEXAS INSTRUMENTS	



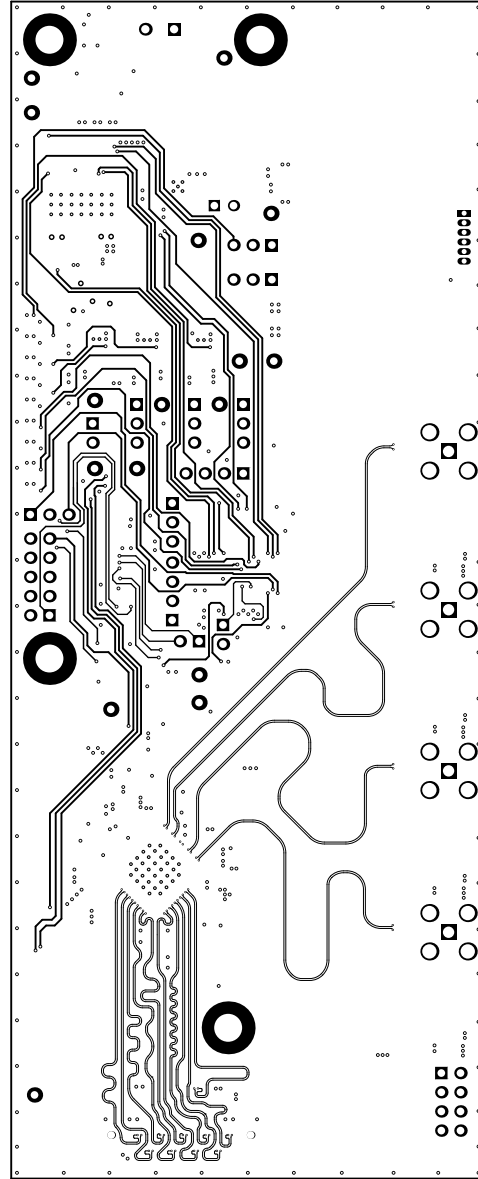
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01323	REV: E1.0	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 01323		
PLOT NAME = Top Solder Mask	GENERATED : 10/19/2017 2:04:28 PM		TEXAS INSTRUMENTS



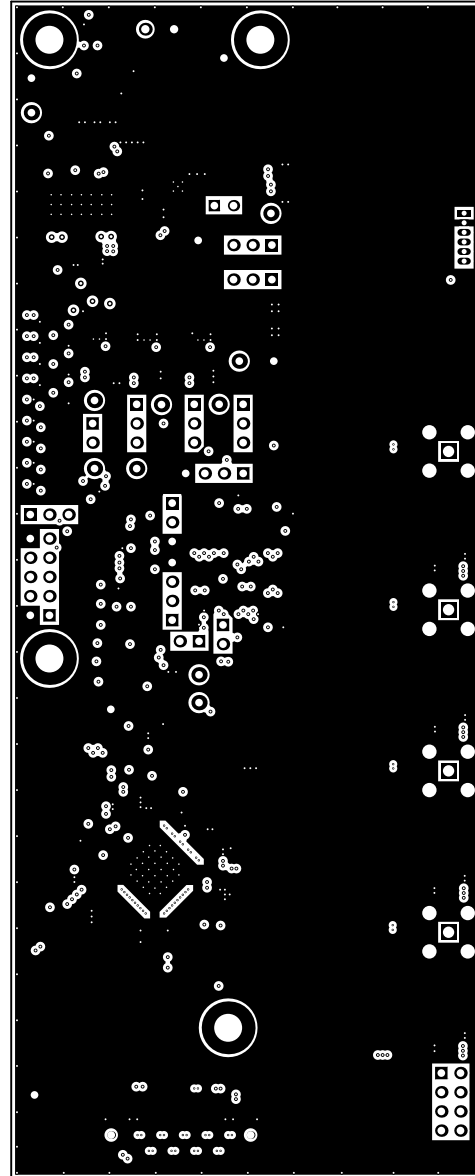
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01323	REV: E1.0	SUN REV: Not In VersionControl
LAYER NAME = Layer 1 - Top Layer	TID #: 01323		
PLOT NAME = Top Layer	GENERATED : 10/19/2017 2:04:29 PM		TEXAS INSTRUMENTS



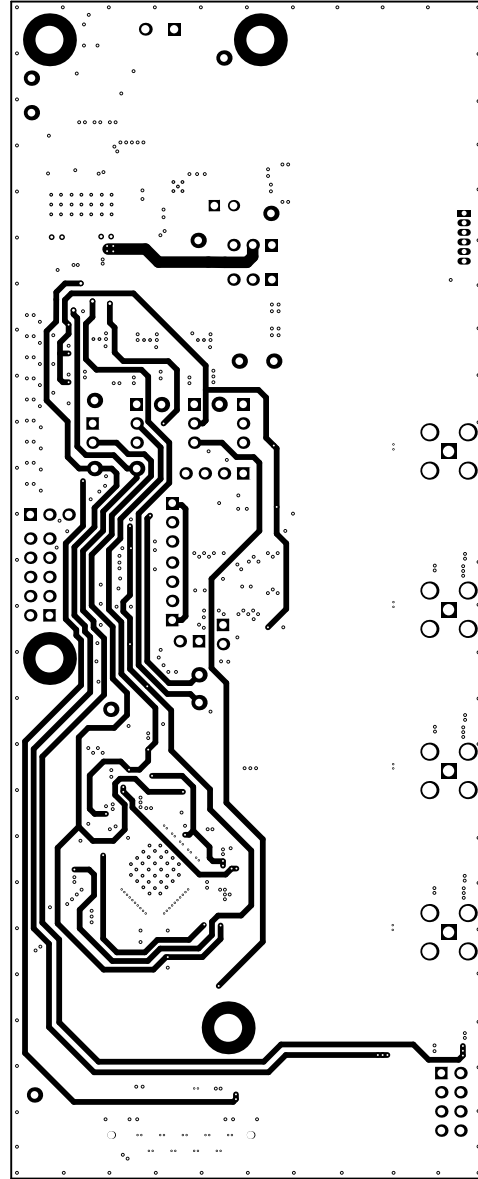
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01323	REV: E1.0	SUN REV: Not In VersionControl
LAYER NAME = Layer 2 - GND	TID #: 01323		
PLOT NAME = Signal Layer 1	GENERATED : 10/19/2017 2:04:30 PM		TEXAS INSTRUMENTS



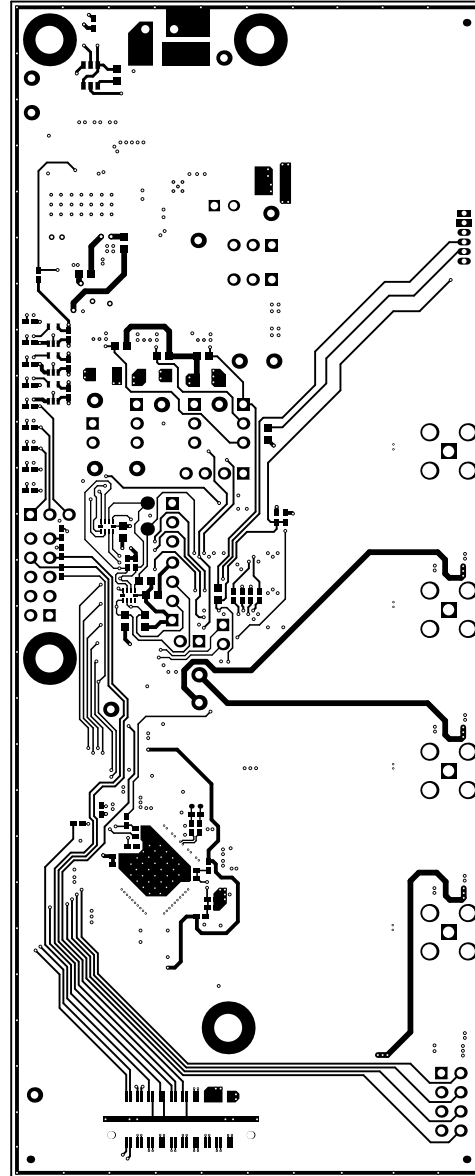
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01323	REV: E1.0	SUN REV: Not In VersionControl
LAYER NAME = Layer 3 - Sensitive	TID #: 01323		
PLOT NAME = Signal Layer 2	GENERATED : 10/19/2017 2:04:31 PM		TEXAS INSTRUMENTS



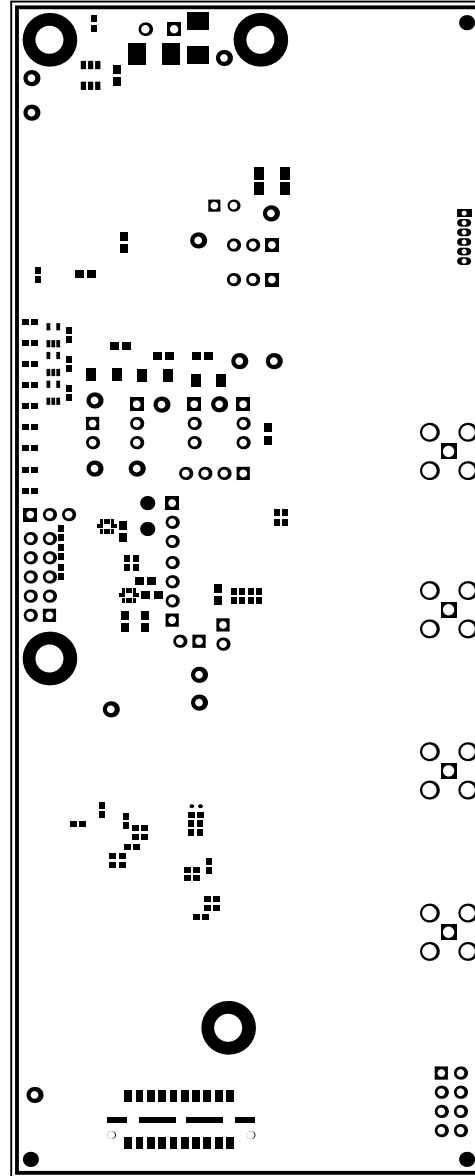
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01323	REV: E1.0	SUN REV: Not In VersionControl
LAYER NAME = Layer 4 - GND	TID #: 01323		
PLOT NAME = Signal Layer 3	GENERATED : 10/19/2017 2:04:32 PM		TEXAS INSTRUMENTS



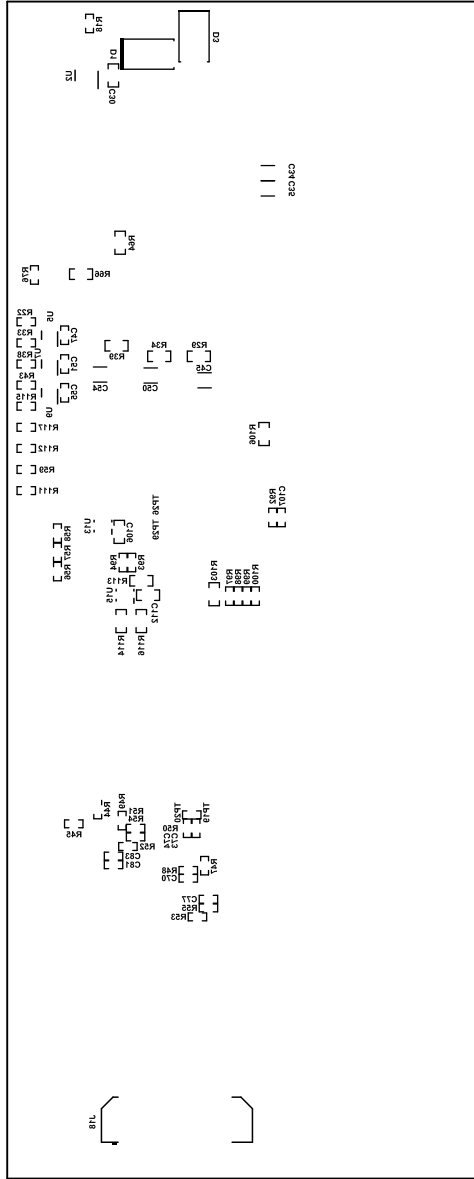
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01323	REV: E1.0	SUN REV: Not In VersionControl
LAYER NAME = Layer 5 - PWR	TID #: 01323		
PLOT NAME = Signal Layer 4	GENERATED : 10/19/2017 2:04:33 PM		TEXAS INSTRUMENTS



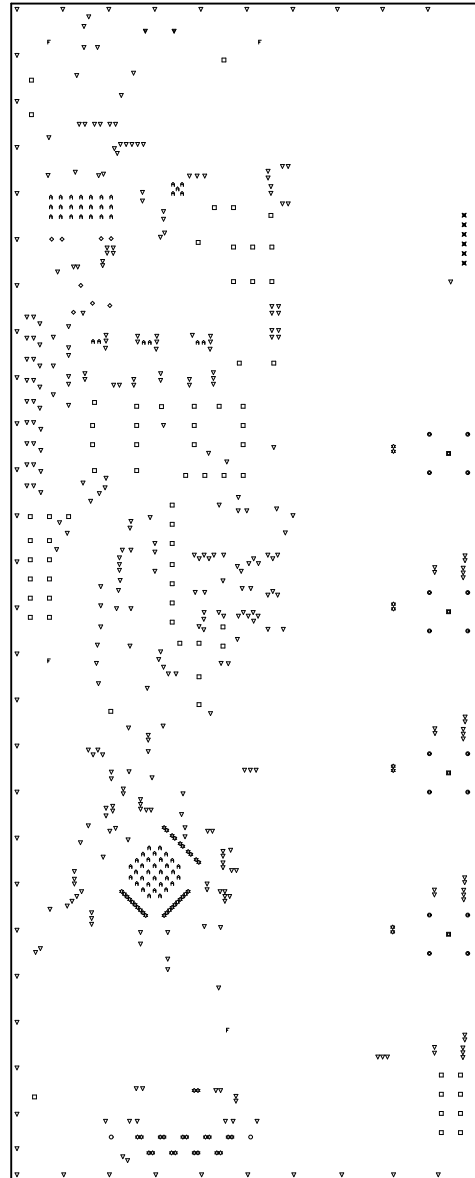
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01323	REV: E1.0	SUN REV: Not In VersionControl
LAYER NAME = Layer 6 - Bottom Layer	TID #: 01323		
PLOT NAME = Bottom Layer	GENERATED : 10/19/2017 2:04:33 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01323	REV: E1.0	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 01323		
PLOT NAME = Bottom Solder Mask	GENERATED : 10/19/2017 2:04:34 PM		TEXAS INSTRUMENTS

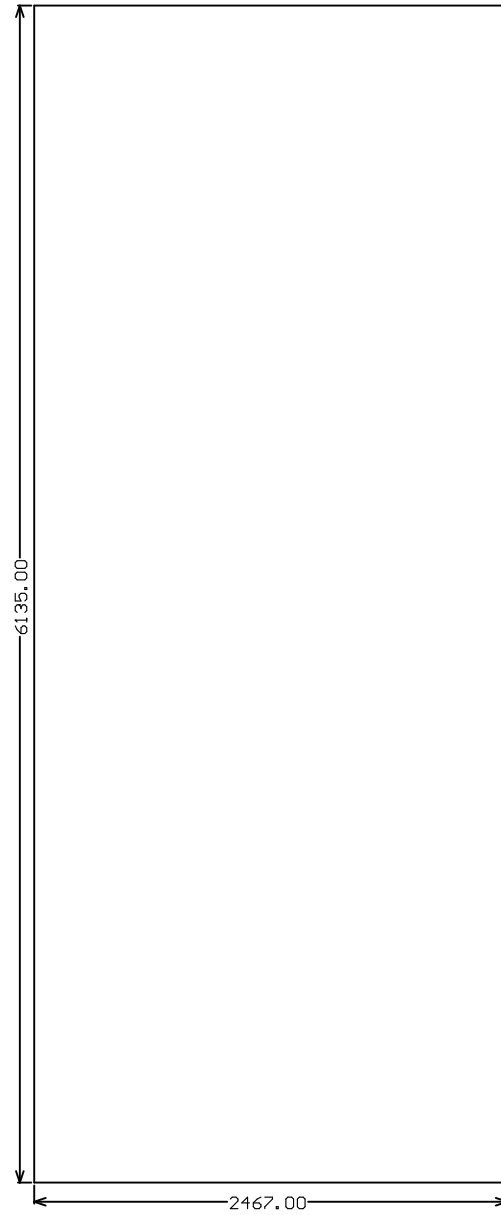
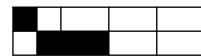


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01323	REV: E1.0	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: 01323		
PLOT NAME = Bottom Overlay	GENERATED : 10/19/2017 2:04:35 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
○	2	40.16mil (1.020mm)	NPTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
☆	58	6.00mil (0.152mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
▽	64	7.87mil (0.200mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
▽	397	10.00mil (0.254mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
◇	8	15.00mil (0.381mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
×	6	26.00mil (0.660mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
□	71	40.00mil (1.016mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
▽	2	43.31mil (1.100mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
■	4	59.06mil (1.500mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
●	16	74.80mil (1.900mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
F	4	145.67mil (3.700mm)	PTH	Round	Layer 1 - Top Layer - Layer 6 - Bottom Layer	
	632 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01323	REV: E1.0	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 01323		
PLOT NAME = Drill Drawing	GENERATED : 10/19/2017 2:04:36 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01323	REV: E1.0	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: 01323		
PLOT NAME = Board Dimensions	GENERATED : 10/19/2017 2:04:38 PM	TEXAS INSTRUMENTS	

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